

<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT5683273

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
KWAN HENG CHAN	11/23/2016
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	PANEL AIR DUCT ENGINEERING
<b>Street Address:</b>	101 PIONEER ROAD
<b>City:</b>	SINGAPORE
<b>State/Country:</b>	SINGAPORE
<b>Postal Code:</b>	639581
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16319698
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(770)951-0933
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	7709339500
<b>Email:</b>	sofia.miller@thomashorstemeyer.com
<b>Correspondent Name:</b>	THOMAS HORSTEMEYER
<b>Address Line 1:</b>	3200 WINDY HILL ROAD SE
<b>Address Line 2:</b>	SUITE 1600E
<b>Address Line 4:</b>	ATLANTA, GEORGIA 30339
<b>ATTORNEY DOCKET NUMBER:</b>	171906-1010
<b>NAME OF SUBMITTER:</b>	MICHAEL J. D'AURELIO
<b>SIGNATURE:</b>	/Michael J. D'Aurelio/
<b>DATE SIGNED:</b>	08/23/2019
<b>Total Attachments: 4</b>	
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**DEED OF ASSIGNMENT**

**THIS DEED** made the 23<sup>rd</sup> of November two thousand and sixteen (2016)

**BETWEEN,**

**CHAN, Kwan Heng  
101 Pioneer Road,  
Singapore 639581,  
Singapore**

[hereinafter referred to as "the Assignor"]

**AND**

**Panel Air Duct Engineering  
101 Pioneer Road,  
Singapore 639581,  
Singapore**

[hereinafter referred to as "the Assignee"]

**WHEREAS** the Assignor is the inventor of the applications identified in Exhibit A (hereinafter referred to as "the Applications")

**AND WHEREAS** the Assignor has agreed to assign to the Assignee and the Assignee desires to take assignment of all rights, title and interest of the Assignor in the Applications,

**NOW THIS DEED WITNESSETH**

1. In consideration of the sum of one dollar (\$1) and other good and valuable consideration receipt of which is hereby acknowledged by the Assignor, the Assignor hereby assigns to the Assignee all of his rights, title and interest in and to the Applications including:

- (a) all rights and powers to make one or more applications for Letters Patent, Design or other forms of protection in the name of the Assignee in Singapore, the United States of America and in any other country of the world in respect of the Invention or Design, and all rights, title and interest in and to any Letters Patent, Design or other form of protection to mature from any such applications,
- (b) the rights and powers to prosecute the Application and all rights, title and interest in and to any Patents or Design granted thereon together with any extension of the term of any such Patents or Design Patent as may be granted, SAVE THAT nothing in this Deed shall prevent the filing or proceeding of an Application to which this Deed relates, in the name of the Assignor or Inventor where such filing or proceeding of such Application is beneficial to the interests of the Assignee
- (c) the rights and powers to seek protection in countries other than Singapore by way of Patent, Petty Patent, Utility Model, Design or other appropriate form of protection for the Invention or Design, by way of application(s) for such protection made to the appropriate authorities in such other country or countries as the Assignee in its complete discretion may elect, whether or not any such foreign application(s) be made claiming International Convention priority from the Application hereby assigned
- (d) any Copyright owned by the Assignor in and to any drawings relating to the subject matter of the Invention or Design together with the rights and powers such as subsist at the date of this Deed
- (e) to apply for registration of Copyright, Design, Design-Patent or like protection in the name of the Assignee in Singapore and in any other country of the world in respect of the subject matter of the said drawings and to any registration of Copyright, Design-Patent or like protection which matures from any such application, together with the rights to sue in respect of any infringement of that Copyright which may have occurred before the date of this Deed

2. The Assignor agrees, at the expense of the Assignee, to sign, execute and deliver all documents, forms and papers reasonably required to be produced or obtained by the Assignee in connection with any application for Letters Patent or Design, or other form of protection for the subject matter of the Invention or Design, in Singapore or elsewhere.

IN WITNESS WHEREOF the Assignor and Assignee executed this Deed the day and year first hereinbefore written.

ASSIGNOR

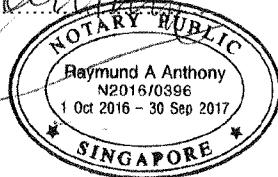
SIGNED, SEALED and DELIVERED

By the said

**CHAN, Kwan Heng**

in the presence of:

.....  
(Witness)



.....

ASSIGNEE

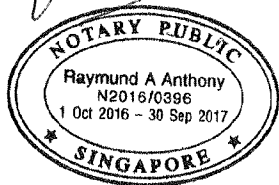
FOR AND ON BEHALF OF

By the said

**Panel Air Duct Engineering**

in the presence of:

.....  
(Witness)



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Exhibit A

No.	Country	Title	Application no.	Filing date	Property Type
1	Singapore	Panel End Mounting Panel Flange	30201602576T	24 May 2016	Design
2	Singapore	Panel End Mounting Panel Flange	30201602753Q	25 July 2016	Design
3	Singapore	A Duct Panel	10201606130V	25 July 2016	Patent
4	Australia	A Duct Panel	2016101773	6 October 2016	Innovation Patent